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Atty Ref/Docket No.: 303.663US1



101310573

To the Honorable Commissioner of Patents and Trademarks

or copy thereof.

1. Name of conveying party(ies):

Eugene H. Cloud

3-3-00

Additional name(s) of conveying party(ies) attached? []Yes [X]No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: March 1, 2000

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Street Address: 8000 South Federal Way

City: Boise State: ID ZIP: 83716-9632

Additional name(s) & address(es) attached? []Yes [X]No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: March 1, 2000

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? []Yes [X]No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Viet V. Tong

Address: Schwegman, Lundberg, Woessner & Kluth, P.A.
P.O. Box 2938
Minneapolis, MN 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Please charge any additional fees or credit any overpayments to our
Deposit account number: 19-0743

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Viet V. Tong/Reg. No. P-45,416
Name of Person Signing

[Signature]
Signature

March 3, 2000
Date

Total number of pages including cover sheet: 3

OMB No. 0651-0011 (exp. 4/94)

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ASSIGNMENT

WHEREAS, I, Eugene H. Cloud, residing at 2145 Mortimer Drive, Boise, ID 83712, made certain new and useful inventions and improvements for which I executed an application for Letters Patent of the United States on Even Date Herewith, which is entitled HIGH DENSITY STORAGE SCHEME FOR SEMICONDUCTOR MEMORY.

AND WHEREAS, Micron Technology, Inc., a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 8000 South Federal Way, Boise, ID 83716-9632, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, I have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, I do hereby agree that I and my executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

